

DESCRIPTION

The S3AF~S3MF are available in SMAF package

FEATURES

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Juntion
- Easy to pick and place
- Available in SMAF package

ORDERING INFORMATION

Package Type	Part Number				
	S3AF				
SMAF	S3BF				
	S3DF				
	S3GF S3JF				
					S3KF
	S3MF				
	Note	SPQ: 3,000pcs/Reel			
AiT provides all RoHS Compliant Products					

MECHANICAL DATA

Case: SMAF

Terminals: Solderable per MIL-STD-750,

Method 2026

Approx. Weight: 27mg 0.00086oz

PIN DESCRIPTION



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MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %

Single phase nair-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.									
Parameter	Symbol	S3AF	S3BF	S3DF	S3GF	S3JF	S3KF	S3MF	Unit
Maximum Repetitive Peak Reverse									
Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
		0.5	70	4.40	000	400	500	700	
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified							_		
Current at T _A =65°C	l _{F(AV)}	3							Α
Peak Forward Surge Current 8.3 ms									
Single Half Sine Wave Superimposed	I _{FSM}	100							А
on Rated Load(JEDEC Method)									
Maximum Instantaneous Forward	\/_	1.2						\ \	
Voltage at 3A	VF								V
Maximum DC Reverse Current @T _A =25°C	I_	5							μА
at Rated DC Blocking Voltage @T _A =125°C	IR	I _R 250							
Typical junction capacitance NOTE1	Сл	53						pF	
T : - 144 1 : -4 NOTE?	1	13						°C/W	
Typical thermal resistance NOTE2	R _θ ја	47							
Operating and Storage Temperature	T _J ,	-55 to 150				°C			
Range	T_{STG}								

NOTE1: Measured at 1 MHz and applied reverse voltage of 4 V DC

NOTE2: Thermal resistance from junction to ambient at 0.375" (9.5 mm) lead length, P.C.B. mounted

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TYPICAL CHARACTERISTICS

Figure 1. Forward Current Derating Curve

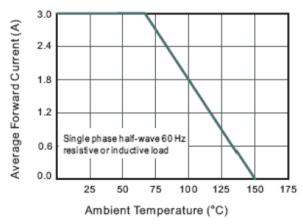


Figure 3. Typical Forward Characteristic

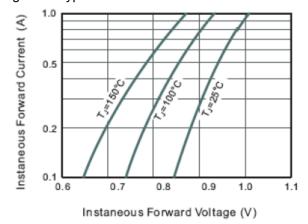


Figure 2. Typical Instaneous Reverse

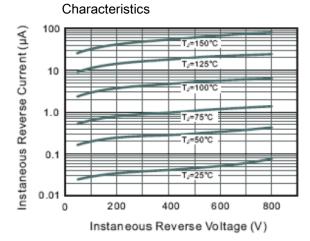
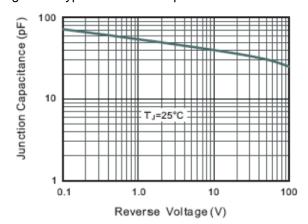


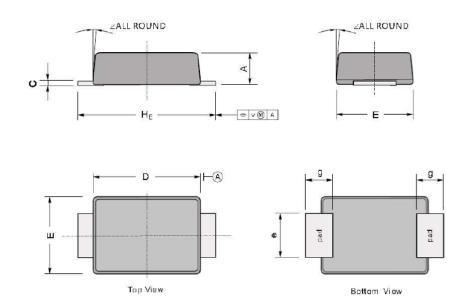
Figure 4. Typical Junction Capacitance



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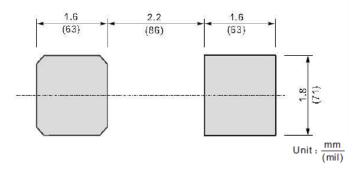
PACKAGE INFORMATION

Dimension in SMAF Package (Unit: mm/mil) Plastic surface mounted package; 2 leads



UNIT		Α	O	D	Е	е	g	HE	∠
mm	max	1.1	0.20	3.7	2.7	1.6	1.2	4.9	7°
	min	0.9	0.12	3.3	2.4	1.3	0.8	4.4	
mil	max	43	7.9	146	106	63	47	193	,
	min	35	4.7	130	94	51	31	173	

The recommended mounting pad size



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